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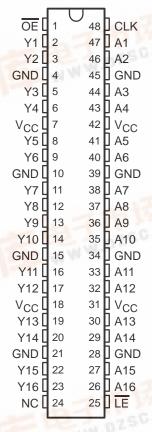
- Member of the Texas Instruments Widebus™ Family
- EPIC ™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Ideal for Use in PC100 Register DIMM
- Designed to Comply With JEDEC 168-Pin and 200-Pin SDRAM Buffered DIMM Specification
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

This 16-bit universal bus driver is designed for 1.65-V to 3.6-V V_{CC} operation.

Data flow from A to Y is controlled by the output-enable (OE) input. The device operates in the transparent mode when the latch-enable (LE) input is low. When LE is high, the A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When OE is high, the outputs are in the high-impedance state.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



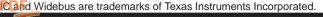
NC - No internal connection

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ALVC16334 is characterized for operation from -40°C to 85°C.

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Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

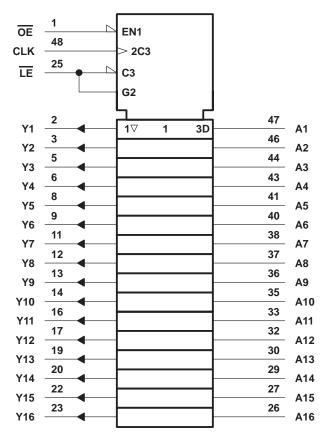


FUNCTION TABLE

	INF	ОИТРИТ		
ŌĒ	LE	CLK	Α	Y
Н	Χ	Х	Χ	Z
L	L	X	L	L
L	L	X	Н	н
L	Н	\uparrow	L	L
L	Н	\uparrow	Н	н
L	Н	L or H	Χ	Y ₀ †

[†] Output level before the indicated steady-state input conditions were established

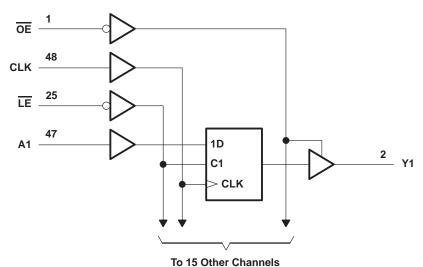
logic symbol‡



[‡] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)		–0.5 V to 4.6 V
Output voltage range, V _O (see Notes 1 and 2)		. -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)		–50 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Continuous output current, IO		±50 mA
Continuous current through each V _{CC} or GND		±100 mA
Package thermal impedance, θ _{JA} (see Note 3):	DGG package	89°C/W
	DGV package	93°C/W
	DL package	94°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		1.65	3.6	V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
VIH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2	3.6	
	Low-level input voltage Volume Voltage Input voltage Output voltage Volume Voltage	V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	
VIL	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
	H High-level input voltage Low-level input voltage Input voltage Output voltage High-level output current V V V V V V V V V V V V V	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
٧ı	Input voltage		0	VCC	V
Vo	Output voltage		0	Vcc	V
		V _{CC} = 1.65 V		-4	
l	High level output current	V _{CC} = 2.3 V		3.6 CC 0.35 × V _{CC} 0.7 0.8 V _{CC} V _{CC} -4 -12 -12 -12 -24 4 12 12 24 10	mA
ЮН	riigir-ievei output current	VCC = 1.65 V to 1.95 V 0.65 × VCC VCC = 2.3 V to 2.7 V 1.7 VCC = 2.7 V to 3.6 V 2 VCC = 1.65 V to 1.95 V 0.35 × VCC VCC = 2.3 V to 2.7 V 0.7 VCC = 2.7 V to 3.6 V 0.8 VCC = 1.65 V -4 VCC = 2.3 V -12 VCC = 3 V -24 VCC = 1.65 V 4 VCC = 2.3 V 12 VCC = 2.7 V 12 VCC = 2.7 V 12 VCC = 3 V 24	IIIA		
		V _{CC} = 3 V		3.6 CC 0.35 × V _{CC} 0.7 0.8 V _{CC} V _{CC} -4 -12 -12 -24 4 12 12 24 10	
		V _{CC} = 1.65 V		4	
	Low lovel output ourrent	V _{CC} = 2.3 V		12	mA
IOL	Low-level output current	V _{CC} = 2.7 V		12	IIIA
		V _{CC} = 3 V		24	
Δt/Δν	Input transition rise or fall rate			10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CO	NDITIONS	VCC	MIN	TYP [†]	MAX	UNIT
		I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2		
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2			
		$I_{OH} = -6 \text{ mA}$		2.3 V	2			
Voн		2.3 V	1.7			V		
· On		$I_{OH} = -12 \text{ mA}$		2.7 V	2.2			
				3 V	2.4			
		I _{OH} = -24 mA	3 V	2				
Vo.		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2		
		$I_{OL} = 4 \text{ mA}$	1.65 V			0.45	٧	
		$I_{OL} = 6 \text{ mA}$	2.3 V			0.4		
VOL		I _{OL} = 12 mA	2.3 V			0.7	ı v	
		10L = 12 111A	2.7 V			0.4		
		I _{OL} = 24 mA	3 V			0.55		
Тį		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ
loz		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ
Icc		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ
∆lcc		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ
Ci	Control inputs			3.3 V	5			ηE
<u> </u>	Data inputs	$V_I = V_{CC}$ or GND		3.5 V	5.5			pF
Co	Outputs	$V_O = V_{CC}$ or GND		3.3 V		7.5	·	pF

 $[\]dagger$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

			V _{CC} =	1.8 V	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f _{clock} Clock frequency			‡		150		150		150	MHz			
	Pulse duration	LE low		‡		3.3		3.3		3.3		ne	
lw	t _W Pulse duration CLK hig			‡		3.3		3.3		3.3		ns	
		Data before CLK↑		‡		1.4		1.7		1.5			
t _{su}	Setup time	Setup time Data before $\overline{\text{LE}} \uparrow$	CLK high	‡		1.2		1.6		1.3		ns	
			CLK low	‡		1.4		1.5		1.2			
	t _h Hold time	Data after CLK↑		‡		0.9		0.9		0.9			
th		Data after LE↑	CLK high or low	‡	·	1.1		1.1	·	1.1		ns	

[‡] This information was not available at the time of publication.



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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(IIVFOT)	(OUTFUT)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			†		150		150		150		MHz
^t pd	А			†	1	3.7		3.6	1.1	3.3	
	LE	Y		†	1	4.8		5	1.3	4.4	ns
	CLK			†	1	4.4		4.5	1	4.1	
t _{en}	ŌĒ	Υ		†	1	5.4		5.4	1.1	4.6	ns
t _{dis}	ŌĒ	Y		†	1	4.1		4.5	1.7	4.4	ns

[†] This information was not available at the time of publication.

switching characteristics from 0°C to 65°C, C_L = 50 pF

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1	UNIT	
	(1141 01)	(0011 01)	MIN	MAX	
[†] pd	A	Y	1.2	3.2	ns
	CLK	Y	1.1	4	ns

operating characteristics, $T_A = 25^{\circ}C$

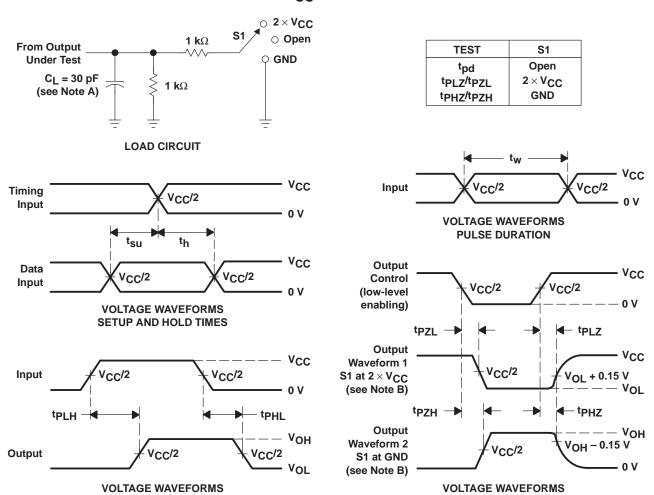
PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT
TANAMETER		TEST CONDITIONS	TYP	TYP	TYP	ONII	
<u> </u>	Power dissipation	Outputs enabled	Cı = 0. f = 10 MHz	†	31	36	pF
C _{pd}	capacitance	Outputs disabled	$C_L = 0$, $f = 10 \text{ MHz}$	†	7	11	pr

[†] This information was not available at the time of publication.

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ENABLE AND DISABLE TIMES

PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.8 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.

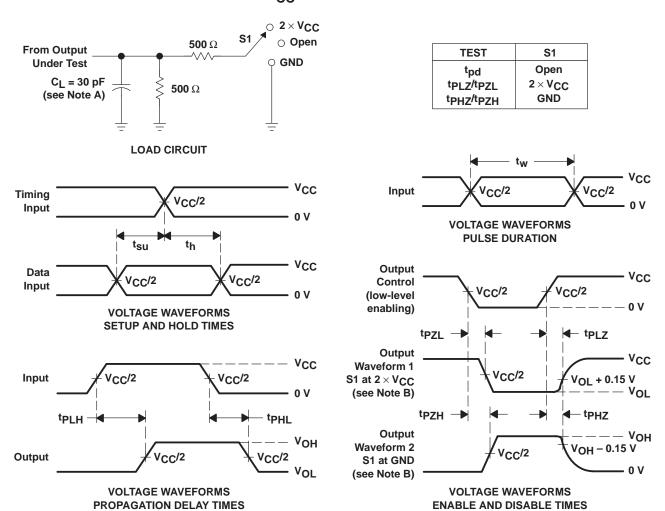
PROPAGATION DELAY TIMES

- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

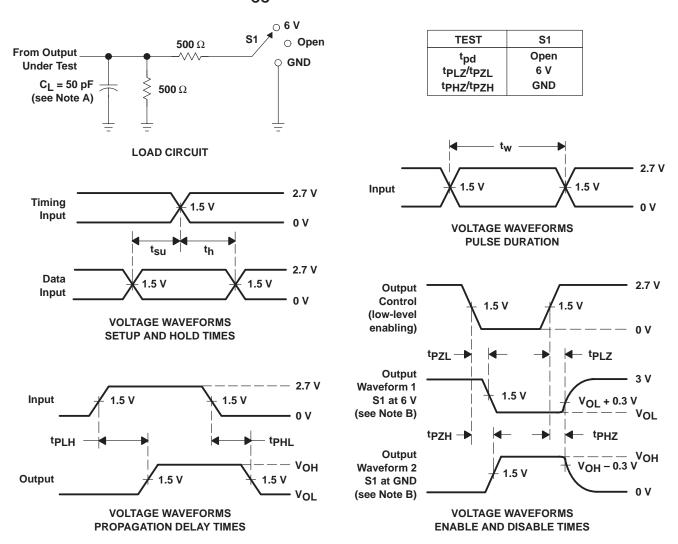


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq 2.5 \text{ ns}$, $t_{f} \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms



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